



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-06-25
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32H503KBU7	61MG*474XXXY	A	998Z	2025-06-25
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	50	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFN	5x5	32	Flat	
Comment	Package : A0B8 UFQFPN 5X5X0.55 32L 0.5 MM PITCH 8202208			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-21st January 2025				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	61MG*474XXY		50.2243		6000000.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	2.115	mg	supplier	die	Silicon (Si)	7440-21-3		2.034	mg	961672	40493.03
				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	4229	178.07
				supplier	metallization	Copper (Cu)	7440-50-8		0.027	mg	12619	531.35
				supplier	passivation	Nickel (Ni)	7440-02-0		0.000	mg	67	2.82
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.005	mg	2148	90.45
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	537	22.61
				supplier	metallization	Tungsten (W)	7440-33-7		0.000	mg	67	2.82
				supplier	Passivation	Silicon Nitride	12033-89-5		0.006	mg	3021	127.20
				supplier	Passivation	Silicon Oxide	7631-86-9		0.033	mg	15640	658.55
				supplier	Organic Compounds	Acrylic resin	Proprietary		0.019	mg	70000	377.32
Glue Epoxy (EN4900GC)	Other Organic Materials	0.271	mg	supplier	Organic Compounds	Polybutadiene derivative	Proprietary		0.005	mg	20000	107.81
				supplier	Organic Compounds	Butadiene copolymer	Proprietary		0.004	mg	15000	80.85
				supplier	Organic Compounds	Acrylate	Proprietary		0.015	mg	54000	291.08
				supplier	Organic Compounds	Epoxy resin	Proprietary		0.008	mg	30000	161.71
				supplier	Organic Compounds	Peroxide	Proprietary		0.002	mg	8000	43.12
				supplier	Organic Compounds	Additive	Proprietary		0.005	mg	18000	97.03
				supplier	Metals	Silver	7440-22-4		0.213	mg	785000	4231.39
				supplier	Organic Compounds	Epoxy Resin A	Proprietary		0.920	mg	55000	18311.20
Encapsulation (EME- G631BQ-CJ)	Other Organic Materials	16.721	mg	supplier	Organic Compounds	Phenol Resin B	Proprietary		0.351	mg	21000	6991.55
				supplier	Organic Compounds	Phenol Resin	Proprietary		0.920	mg	55000	18311.20
				supplier	Glass	Silica(Amorphous)A	60676-86-0		12.859	mg	769000	256023.92
				supplier	Glass	Silica(Amorphous)B	7631-86-9		1.254	mg	75000	24969.82
				supplier	Organic Compounds	Metal Hydroxide	Proprietary		0.334	mg	20000	6658.62
				supplier	Organic Compounds	Carbon Black	1333-86-4		0.084	mg	5000	1664.65
Bonding wires (Cu)	Bonding Wire	0.199	mg	supplier	Metals	Copper	7440-50-8		0.192	mg	965500	3818.25
				supplier	Metals	Palladium	7440-05-3		0.006	mg	31000	122.60
				supplier	Metals	Gold	7440-57-5		0.001	mg	3500	13.84
				supplier	Metals	Tin	7440-31-5		0.719	mg	1000000	14314.38
Plating anode (Sn)	Other inorganic materials	0.719	mg	supplier	Metals	Copper	7440-50-8		27.698	mg	917140	551478.80
Leadframe (C7025 + Ag)	Copper & its alloys	30.200	mg	supplier	Metals	Nickel	7440-02-0		0.680	mg	22500	13529.31
				supplier	Metals	Silicon	7440-21-3		0.079	mg	2600	1563.39
				supplier	Metals	Magnesium	7439-95-4		0.035	mg	1150	691.50
				supplier	Metals	Silver	7440-22-4		1.710	mg	56610	34039.75